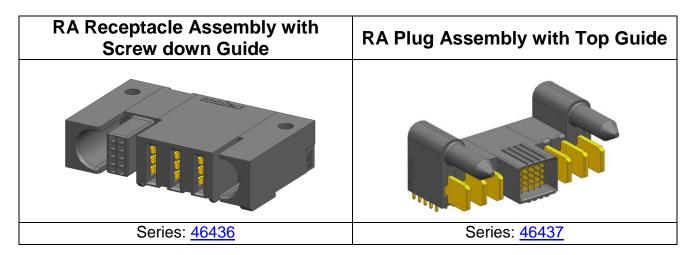


EXTREME TEN60POWER™

Board-To-Board CONNECTOR SYSTEM

RA Receptacle Assembly with Top Guide	RA Receptacle Assembly with Side Guide
Series: <u>46436</u>	Series: <u>46436</u>

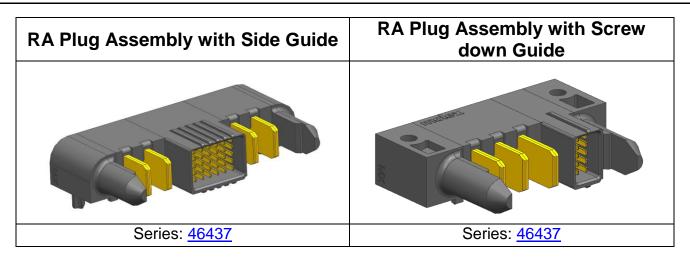


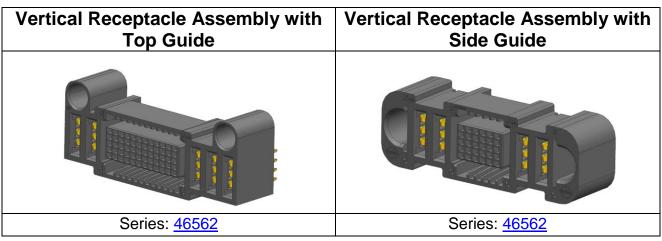
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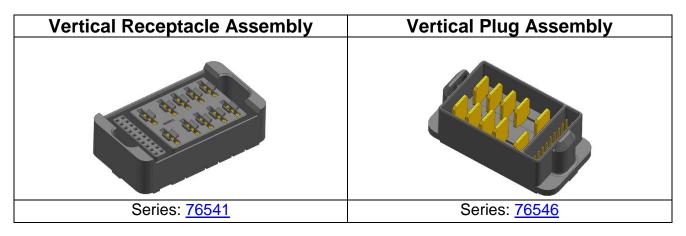


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TEMPLATE FILE	NAME: 1703070003 REV A	1				1	

PRODUCT SPECIFICATION



RA Power Plug Modules (1-10 ckt)



RA Power Receptacle Modules (1-10 ckt)



Vertical Power Receptacle Modules (1-10 ckt)

Note: All power modules are available at 5.5 mm pitch for DC (low voltage) applications and 7.5 mm pitch AC (high voltage) application. See pg. 16 for recommended PCB lay-outs.

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PRODUCT SPECIFICATION





RA Signal Plug Modules (6-36 ckt) or RA HDS Plug Module (10-60 ckt)





RA Signal Receptacle Modules (6-36 ckt) or RA HDS Receptacle Module (10-40 ckt)





Vertical Signal Recept. Modules (6-36 ckt) or Vertical HDS Recept. Module (10-60 ckt)

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PRODUCT SPECIFICATION

1.0 SCOPE

The specification covers the performance requirements and test methods of Ten60Power and signal modular board to board interconnect systems.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER (S)

This specification covers following board to board configuration Right Angle (RA) Plug assembly mated to RA Receptacle assembly (Coplanar configuration)

46436-XXXX	RA Receptacle Side Assembly
46437-XXXX	RA Plug Side Assembly

Right Angle (RA) Plug assembly mated to Vertical Receptacle assembly (Backplane configuration)

46562-XXXX	Vertical Receptacle Side Assembly
46437-XXXX	RA Plug Side Assembly

Vertical Plug Assy mated to Vertical Receptacle Assy (Mezzanine configuration)

76541-XXXX	Vertical Receptacle Side Assembly
76546-XXXX	Vertical Plug Side Assembly

2.2 DIMENSIONS, MATERIALS, PLATINGS

Dimensions: See individual sales drawings.

Plating: Gold on mating surfaces and tin on PC tail with nickel under-plating overall.

2.3 ENVIRONMENTAL CONFORMANCE

To find product compliance information:

- a. Go to molex.com
- b. Enter the part number in the search field.
- c. At the bottom of the page go to "Environmental" to see compliance status.

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PRODUCT SPECIFICATION

2.4 **SAFETY AGENCY LISTINGS**



2.4.1

File Number*: LR-19980 A 000 Class 6233-81

CSA approval meets following standards/test procedures:

- a) CSA std. C22.2 No. 182.3-M1987
- b) UL-1977
- * "C" and "US" mark adjacent to CSA signifies that the product has been evaluated to the applicable CSA and ANSI/UL standards, for use in Canada and US respectively.

CSA	CSA
NON-current interruption	Current interruption
2.5 Amps @ 250V for Legacy Signal ckt	2.5 Amp at 28V for Legacy Signal ckt
4.5 Amps @ 75V for HDS Signal ckt	4.5 Amps @ 28V for HDS Signal ckt
60 Amps @ 600V for power ckt	50 Amps at 60V for power ckt

2.4.2 UL - IEC61984 EU- Certificate Number: UL-EU-01060-A1



UL-CB - Report - E29179 -D1-CB IEC 61984-1

Non-current interruption

7.5 mm Pitch 600 volts AC/DC @60 amps

5.5 mm Pitch 250 volts DC @ 60 amps

Signal

Signal Legacy (3 row) 120 Volts AC/DC @ 60 amps

Signal HDS (5 row) 120 Volts AC/DC @ 1.0 amps

IEC 61984 Certification: Tested to and found in compliance with IEC 61984. Certificate available from Molex upon request. Contact Molex safety agency team for questions regarding certification on specific part numbers.

2.4.3 **UL File Number: E29179**

UI **NON-current interruption**

2.5 Amps @ 250V for Legacy signal ckt 4.5 Amps @ 120V for HDS signal ckt 80 Amps @ 600V for power ckt

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3.0 APPLICABLE DOCUMENTS AND SPECIFICATION

3.1 MOLEX DOCUMENTS

Extreme Ten60Power Connector System Application summary AS-4636-100-001

Molex Solderability Specification SMES-152

Molex Heat Resistance Specification AS-40000-5013

Molex Moisture Technical Advisory AS-45499-001

Molex Package Handling Specification 454990100-PK

ATS – Application Tooling Specification*

*Application Tooling Specification for terminals is not provided in this document. ATS for terminals can be available from respective terminal part number page in Molex.com

3.2 INDUSTRY DOCUMENTS

EIA-364-1000 UL-60950-1 CSA STD. C22.2 NO. 182.3-M1987 IEC 61984 UL-1977

4.0 ELECTRICAL PERFORMANCE RATINGS

4.1 VOLTAGE

Legacy Signal Module: 250 Volts HDS Signal Module: 120 Volts

Power Module: 250 or 600 Volts (Ref. to pads layout in section 7.2)

Connector Rating per UL-1977

Connector voltage rating meets the connector approval level defined by UL 1977, Sect. 11 for spacing per table 11.1. Example: 1.2 mm for \leq 250 volt; 3.2 mm for \geq 250 volt.

Exception taken for spacing less than those specified are permitted, if the device complies with the requirements in the dielectric voltage withstanding test per Sect. 17

Application Voltage Guideline

For application voltage requirements please refer to UL-60950 or other applicable standards, the creepage & clearance also needs to be determined based upon pads/traces on the PCB.

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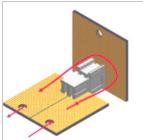
PRODUCT SPECIFICATION

4.2 **CURRENT RATING (MAXIMUM AMPERES)**

Signal Contact: 2.5 Amps **HDS Signal Contact:** 4.5 Amps

Power Contact:

1. Tested with PCB Copper Planes: See charts on page 11.

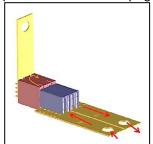


No. of Power Circuits	1-Ckt	2-Ckt	4-Ckt	8-Ckt
Current (Amps)	TBD	85Amps	TBD	TBD

^{**} Tested in accordance with EIA-364-70.

The connector is mounted to a 10-layer PCB with 2oz per layer copper planes. Rating shown represents maximum current of a 2Ckt connector at 30°C rise over ambient temperature.

2. Tested with Copper Coupons: See charts on page 10



No. of Power Contacts	1-Ckt	2-Ckt	4-Ckt	8-Ckt
Current (Amps)	62Amps	59Amps	57Amps	53Amps

^{**}Tested in accordance with EIA-364-70.

The above current ratings are based on testing connectors mounted on a copper coupons. Rating shown represents maximum current carrying capacity at 30°C rise over ambient temperature.

"Current rating is application dependent and should be used as a guideline. Appropriate rating is required per ckt size, ambient conditions, copper trace size on the PCB, gross heating from adjacent modules/components and other factors that influence connector performance".

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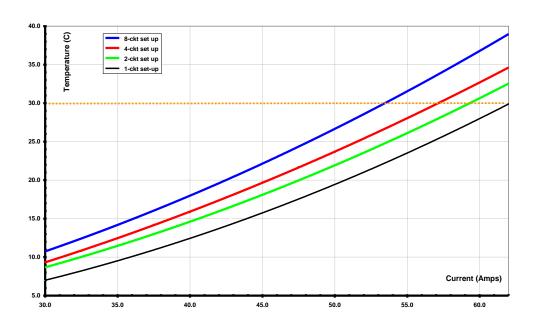
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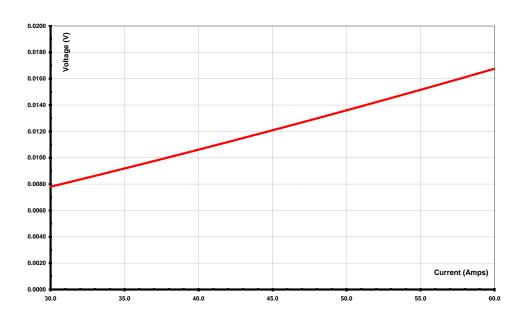


<u>Tested with Copper Coupons</u>

Temperature Rise vs. Current per EIA-364-70



V-drop (max) vs. Current per EIA-364-70



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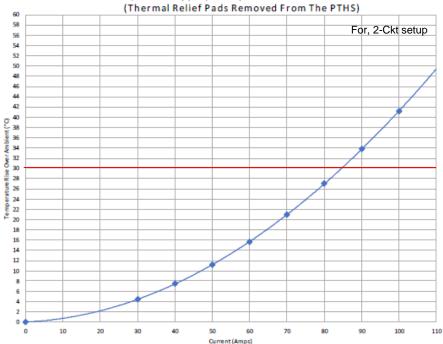
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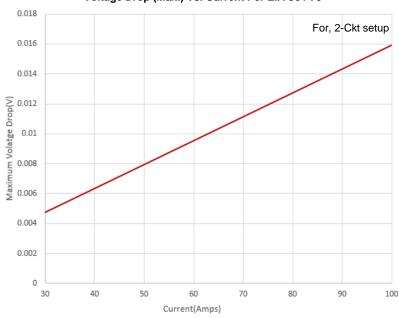
Tested with Copper Planes

Temperature Rise Vs. Current Per EIA-364-70

Ten60 With PCB (20 oz. Copper) - Temperature Rise vs. Current - 4 AWG Wire
(Thermal Relief Pads Removed From The PTHS)



Voltage Drop (Max.) Vs. Current Per EIA-364-70



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4.3 TEMPERATURE

Operating temperature (including T-rise from applied current) is -40° C to +105° C.

Temperature life tested per EIA 364-17 Method A for 240 hrs@105° per table 8 to meet field temperature of 65° C for 10 years life. See page 22 for detail test sequence of EIA-364-1000, Group I.

4.4 **DURABILITY**

Plating Type	Number of Cycles
Gold Plated	200

As tested in accordance with EIA-364-1000 test method C section 7 (see sec 6.2.3 of this specification). Durability per EIA-364-09

5.0 QUALIFICATION

Laboratory condition, sample selection and test sequences are in accordance with EIA-364-1000.

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6.0 **PERFORMANCE**

6.1 **ELECTRICAL PERFORMANCE**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
6.1.1	Initial Contact Resistance (Low Level)	Per EIA-364-23	Signal Contact: 30 m Ω Power Contact: 0.3 m Ω
6.1.2	Voltage Drop (@ Rated Current)	Mate connectors; apply the rated current. Per EIA-364-70	Typical Voltage Drop: Power Contact: see chart, Page 10 & 11
6.1.3	Insulation Resistance	Apply 500 VDC between adjacent terminals or ground. Per EIA-364-21	5,000 M Ω minimum
6.1.4	Dielectric Withstanding Voltage	Apply 1500 VDC for 1 minute between adjacent terminals or ground. Per EIA-364-20	No breakdown
6.1.5	Temperature Rise	Mate connectors Measure T-Rise @ Rated Current After 96 Hours. Per EIA-364-70	30°C T-Rise

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6.2 **MECHANICAL PERFORMANCE**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT			
			Legacy Signal 75 g/ckt Max			
6.2.1	Mating Force, Single Circuit**	Mate connectors at a rate of 25.4±6 mm per minute Per EIA-364-37 Power Vert Recept to R/A Recept to R/A Plug 756 g/ckt Max 443 g/c				
				HDS* 55 g/ckt Max		
	Unmating Force, Single Circuit**		Legacy Signal 23 g/ckt Min			
6.2.2		Unmate connectors at a rate of 25.4±6 mm per minute Per EIA-364-37	Power Vert Receipt to R/A Plug 316 g/ckt Min	Power R/A Recept to R/A Plug 253 g/ckt Min		
			HDS* 25 g Min per Contact			
6.2.3	Durability w/o Environment	Mate connectors 20 cycles at a max rate of 10 cycles per minute Per EIA-364-09	Signal Con	n Change: tact: 10 m Ω act: 0.30 m Ω		
				Power g Min		
6.2.4	Contact	Axial pullout force on the terminal		Power g Min		
0.2.4	Retention	in the housing at a rate of 25.4±6 mm per minute Per EIA-364-29	Vert HDS Signals 544 g Min per coupon			
			R/A HDS Signals 275 g Min per coupon			

^{*} HDS: High Density Signal (5 Row Signal Design)
** Mate/Unmate Data is for 1st Cycle

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6.2 **MECHANICAL PERFORMANCE CONTINUED**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT	
			MIN: 1.10 lbs. (0.5 Kg/pin) (Legacy Signal Module)	
	Min Extraction force for Terminals with Compliant Pins	Pull-out contacts at a rate of	MIN: 1.00 lbs. (0.45 Kg/pin) (HDS Module)	
6.2.5		25.4±6 mm per minute	MIN: 2.37 lbs./pin (1.08 Kg/pin) Vertical Power Receptacle	
			MIN: 2.4 lbs./pin (1.09 Kg/pin) R/A Power Plug	
6.2.6	Vibration (EIA-364-1000)	Mate connectors and vibrate per EIA-364-28 test condition VII-D 15 minutes each axis.	Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω	
6.2.7	Mechanical Shock (EIA-364-1000)	Mate connectors and shock at 50 g with ½ sine wave (11 milliseconds) shocks in the 3 axes (18 shocks total) Per EIA-364-27	Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω	
			MAX: 12.54 lbs/pin (5.7 Kg/ckt) (Legacy Signal Module)	
	Max Insertion		MAX: 10.02 lbs/pin (4.54 kg/ckt)	
6.2.8	force into PCB for	Insert contact at a rate of	(HDS module)	
0.2.8	Terminals with	25.4±6 mm per minute	MAX: 18.5 lbs/pin	
	Compliant Pins		(8.41 kg/pin) (Vertical Pwr Receptacle)	
		MAX: 17.6 lbs		
			(7.98 kg/pin)	
			(R/A Pwr Plug)	

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6.3 **ENVIRONMENTAL PERFORMANCE**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
6.3.1	Thermal Shock (EIA-364-1000)	Mate connectors, expose to 10 cycles from -55°C to 85°C Per EIA-364-32	Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω
6.3.2	Temperature Life (EIA-364-1000)	Mate Connectors, expose to 240 hours at 105°C Per EIA-364-17	Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω
6.3.3	Cyclic Temperature and Humidity (EIA-364-1000)	Mate connectors: expose to 24 cycles from 25 °C / 80% RH to 65 °C / 50% RH Per EIA-364-31	Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω
6.3.4	Dust (EIA-364-1000)	Un-mated 1-hour duration 25°C/50% RH dust mass of 9 g/ft ³ at rate of 300 m/min. Per EIA-364-91	Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω
6.3.5	Mixed Flowing Gas (EIA-364-1000)	168 hours un-mated,168 hours mated, Per EIA-364-65Class II-A	Maximum Change: Signal Contact: 10 m Ω Power Contact: 0.50 m Ω
6.3.6	Solderability Dip Test	Molex test method:	Solder area shell have Min of 95% solder coverage
6.3.7	Resistance to soldering heat from rework	Per EIA-364-61, Test procedure 4 for compliant pin retention force	22.5 lbs. (10.2 Kg) Per Power contact extraction force from PCB
6.3.8	Resistance to soldering heat from rework	Per EIA-364-61, Test procedure 2 (Test Condition II)	No dimensions change No physical damage

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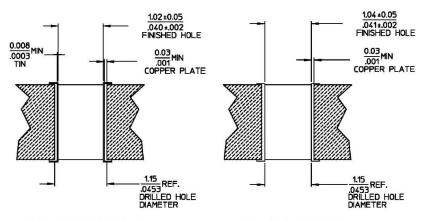
PRODUCT SPECIFICATION

7.0 PRINTED CIRCUIT BOARD SPECIFICATION

7.1 PCB THROUGH HOLE SPEC.

Profile for 1.02 mm (finish) holes:

TIN PLATED OR OSP HOLE DIMENSIONS IN MM/IN

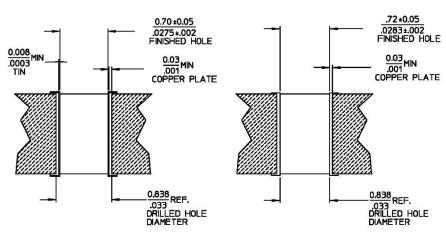


SN/Cu PLATED HOLES

OSP COATED HOLES

Profile for 0.70mm (finish) holes – Signal segment:

TIN PLATED OR OSP HOLE DIMENSIONS IN MM/IN



SN/Cu PLATED HOLES

OSP COATED HOLES

Extreme Ten60Power Connectors Web Page



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E 3	EC No: 637039	PRC	DUC	T SPECIFICATION	N FOR TEN60 P	OWER	17 of 29
L 3	DATE: 2020/05/07	BO	ARD 7	TO BOARD INTER	CONNECT SYS	STEMS	17 01 29
DOCUMENT NUMBER:		DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	APPRO	VED BY:
PS-46436-100		PS	001	GJEEVANSURES	SCS02	HTHY	AGARAJ
TEMPLATE FILE	NAME: 1703070003 REV A						

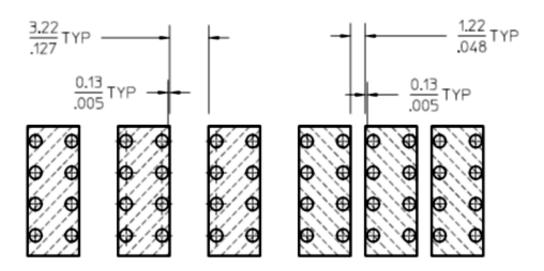
PRODUCT SPECIFICATION

Notes:

- 1. The finished hole size is the critical feature for proper performance of the compliant pin terminal. The reference drill sizes listed are recommended by Molex to achieve the finished PCB hole size.
- 2. Depending on the specific manufacturer's plating process a different drill size can be used to achieve the required finished PCB hole size.

7.2 TYPICAL PCB PADS LAY-OUT AND SIGNAL HOLES LAY-OUT

DIMENSIONS ARE MM/IN



Pads lay-out for power modules with 7.5 mm pitch for high voltage

Pads lay-out for power modules with 5.5 mm pitch for low voltage

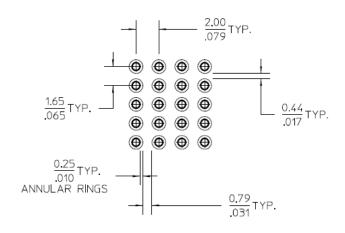
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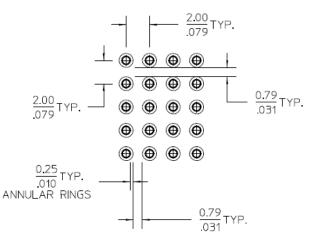
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E3	EC No: 637039	PRC	DUC	T SPECIFICATION	I FOR TEN60 P	OWER	10 of 20
	DATE: 2020/05/07	BO	ARD 1	TO BOARD INTER	CONNECT SYS	STEMS	18 of 29
DOCUMENT NUMBER:		DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	APPRO	VED BY:
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TEMPLATI	E FILENAME: 1703070003 REV A						

PRODUCT SPECIFICATION

Typical Hole Lay-out For 5 row Signal/ HDS modules (0.70mm dia holes)

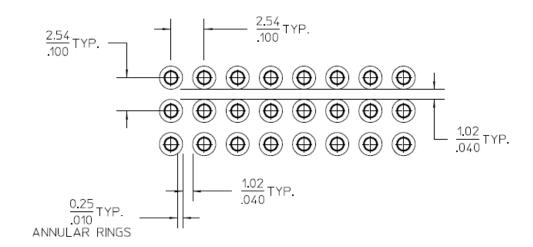


PCB lay-out for HDS modules Vertical conf. only



PCB lay-out for HDS modules R/A conf. only

Typical Signal Hole Lay-out for 2.54mmX2.54mm Signal modules (1.02mm dia holes)



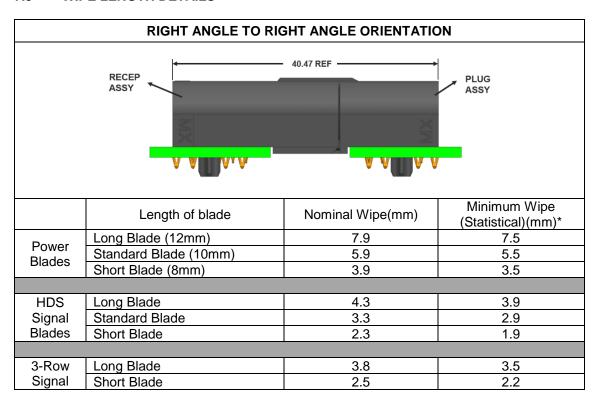
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REVISION	ECM INFORMATION:	TITLE:					SHEET No.
E2	EC No: 637039	PRC	DUC	T SPECIFICATION	N FOR TEN60 P	OWER	40 -4 20
E3	DATE: 2020/05/07	BO	ARD 1	TO BOARD INTER	CONNECT SYS	STEMS	19 of 29
DOCUMENT NUMBER:		DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	APPRO	VED BY:
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PRODUCT SPECIFICATION

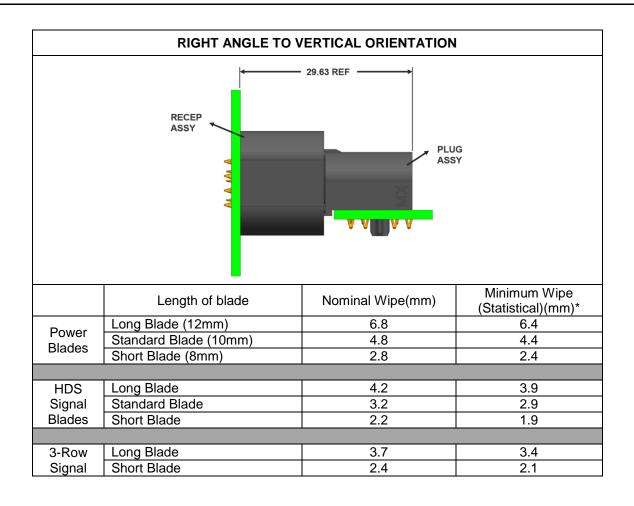
7.3 WIPE LENGTH DETAILS



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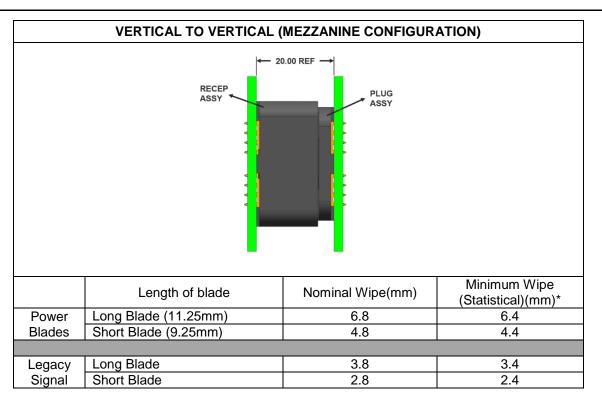
REVISION: ECM INFORMATION:	TITLE:					SHEET No.
E3 EC No: 637039 DATE: 2020/05/07			T SPECIFICATION TO BOARD INTER			20 of 29
DOCUMENT NUMBER:	DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	<u>APPRO</u>	VED BY:
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^{*}Minimum wipe is determined using RSS tolerance analysis for the connector only assuming at mated condition as per reference mating length provided in the illustration above. Mated profile tolerances and system tolerances are not considered into the analysis

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REVISION:	ECM INFORMATION:	TITLE:					SHEET No.
E2	PRC	DUC	T SPECIFICATION	N FOR TEN60 P	OWER	22 of 29	
E3	E3 DATE: 2020/05/07 BOARD TO BOARD INTERCONNECT SYSTEMS						
DOCUMENT NUMBER:		DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	APPRO	VED BY:
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TEMPLATE FILE	NAME: 1703070003 REV A						



7.4 TYPICAL MATING SEQUENCE: POWER & 3 ROW SIGNAL (RA-RA & RA-VERTICAL)

SEQUENCE NO.	SEQUENCE IMAGE	DESCRIPTION
1		Long/Ground power blade(s) (typically used for FMLB) mates first.
2		Short power blade(s) mates second.
3 & 4	3rd	 3. After short power blade(s) the long signal pins (typically the top row) mates third. 4. After long signal pins, the rest of other signal pins will mate.

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E3 EC No: 637039				T SPECIFICATION		_	23 of 29
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DOCUMENT NUMBER:		DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	APPRO	VED BY:
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TEMPLATE FILE	ENAME: 1703070003 REV A						



7.5 TYPICAL MATING SEQUENCE: POWER & 5 ROW SIGNAL (RA-RA & RA-VERTICAL)

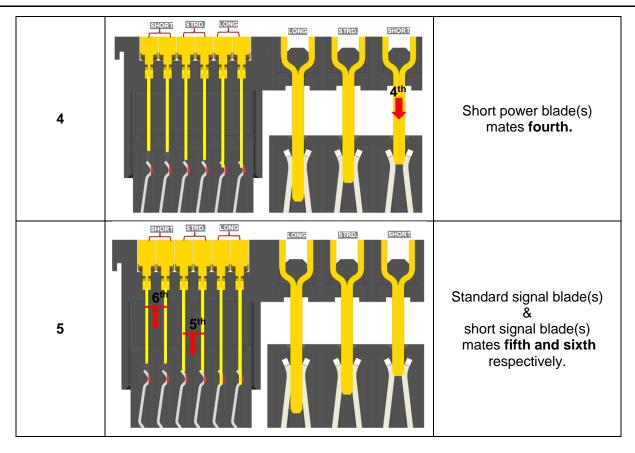
SEQUENCE NO.	SEQUENCE IMAGE	DESCRIPTION
1	SHORT STRD. LONG STRD. SHORT	Long/Ground power blade(s) (typically used for FMLB) mates first.
2	SHORT STRD. LONG STRD. SHORT	Standard power blade(s) mates second.
3	SHORT STRD. LONG LONG STRD. SHORT	Long/Ground signal blade(s) (FMLB) mates third.

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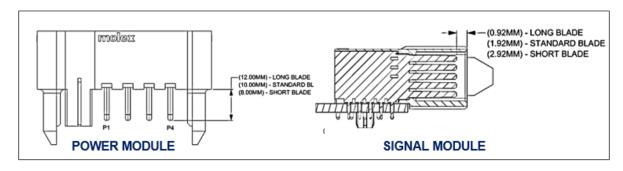
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PRODUCT SPECIFICATION



(Shown mating sequence in 7.4 & 7.5 is typical, custom configurations available on request) (Note – <u>Power</u>: Long Blades-12mm, Standard Blades-10mm & Short Blades-8mm. (Extended length on the mating side).

5 Pin Signal: Long Blades-0.91mm, Standard Baldes-1.92mm & short Blades-2.92mm.(Measured from tip of signal module housing to tip of the blade as per sales drawing).



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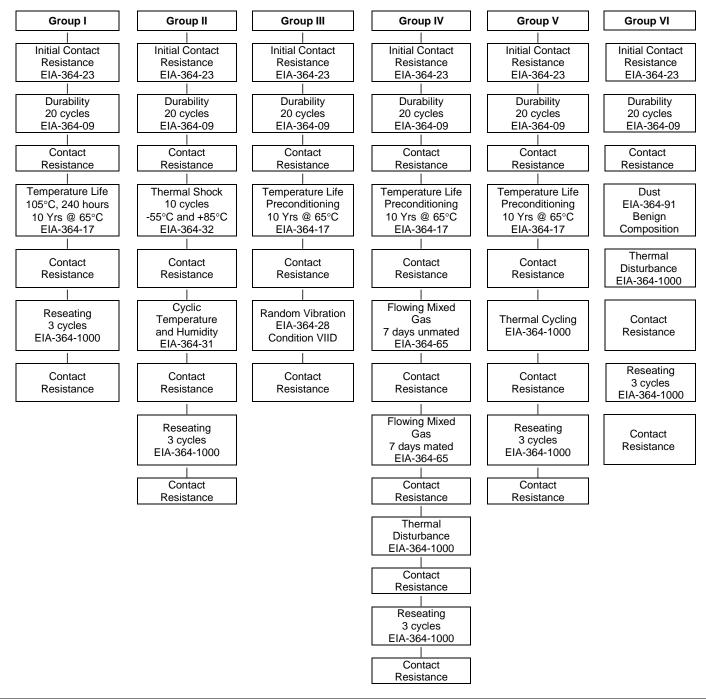


REVISION:	ECM INFORMATION:	TITLE:					SHEET No.
E3	EC No: 637039	PRC	DUC	T SPECIFICATION	N FOR TEN60 P	OWER	25 of 29
	DATE: 2020/05/07	BO	ARD 1	TO BOARD INTER	CONNECT SYS	STEMS	23 01 23
DOCUMENT NUMBER:		DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	<u>APPRO</u>	VED BY:
PS	S-46436-100	PS	001	GJEEVANSURES	SCS02	HTHYA	AGARAJ
TEMPLATE FILE	NAME: 1703070003 REV A						

PRODUCT SPECIFICATION

8.0 TEST SEQUENCE GROUPS

Reliability Test Sequences per EIA-364-1000

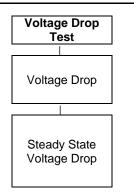


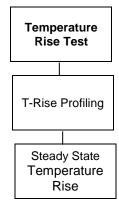
Extreme Ten60Power Connectors Web Page



E3	EC No: 637039		PRODUCT SPECIFICATION FOR TEN60 POWER BOARD TO BOARD INTERCONNECT SYSTEMS					
DATE: 2020/05/07 DOCUMENT NUMBER:		DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	_	VED BY:	
PS-46436-100		PS	001	GJEEVANSURES	SCS02	HTHYA	AGARAJ	
TEMPLATE FIL	ENAME: 1703070003 REV A							

PRODUCT SPECIFICATION





Individual Tests

Connector Mate / Un-mate Force

Contact Retention

Max Insertion force into PCB for terminals with Compliant Pins

Min Extraction force for terminals with Compliant Pins

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E3	EC No: 627020	PRODUCT SPECIFICATION FOR TEN60 POWER BOARD TO BOARD INTERCONNECT SYSTEMS					
DOCUMENT NUMBER:		DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	<u>APPRO</u>	VED BY:
PS-46436-100		PS	001	GJEEVANSURES	SCS02	HTHYA	GARAJ
TEMPLATE F	FILENAME: 1703070003 REV A						

PRODUCT SPECIFICATION

9.0 SOLDER INFORMATION

Per SMES-152 and AS-40000-5013

*These specifications establish standard solderability test methods used to evaluate a products ability to accept molten solder. Solder Process Temperatures and Reflow Solder Profiles will vary based on application, equipment, solder paste, PCB thickness, etc.

9.1 SOLDER PROCESS TEMPERATURES *

Reflow Solder Temperature: 260°C Maximum

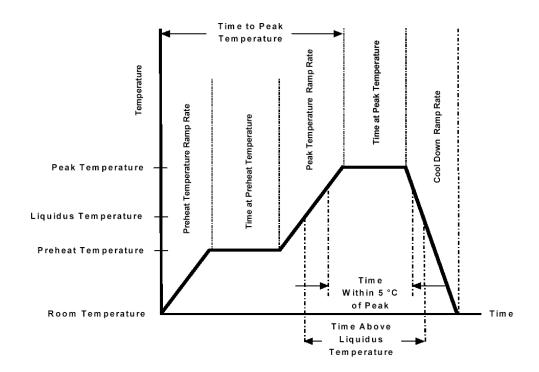
Molex Solderability Specification

SMES-152
(Click Here)

9.2 SOLDERING PROFILE

(This profile is per JEDEC J-STD-020D.1 and it is for guideline only; please see notes for additional information)

Molex Connector Heat Resistance
Specification AS-40000-5013
(Click Here)



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DOCUMENT NUMBER:		DOC TYPE:	DOC PART:	CREATED / REVISED BY:	CHECKED BY:	APPRO	VED BY:
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Description	Requirement
Average Ramp Rate	3°C/sec Max
Preheat Temperature	150°C Min to 200°C Max
Preheat Time	60 to 180 sec
Ramp to Peak	3°C/sec Max
Time over Liquids (217°C)	60 to 150 sec
Peak Temperature	260 +0/-5°C
Time within 5°C of Peak	20 to 40 sec
Ramp - Cool Down	6°C/sec Max
Time 25°C to Peak	8 min Max

Notes:

- 1. Temperature indicated refers to the PCB surface temperature at solder tail area.
- 2. Connector can withstand up to 3 reflow cycles with a cool-down to room temperature in-between.
- Actual reflow profile also depends on equipment, solder paste, PCB thickness, and other components
 on the board. Please consult your solder paste & reflow equipment manufacturer for their
 recommendations to adopt a suitable process.

10.0 PACKAGING

Parts shall be packaging to protect the parts from damage during standard shipping, storage, and handling. Refer Molex.com specific part number webpage to get the exact packaging document for that item.

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E3	EC No: 637039 DATE: 2020/05/07	PRODUCT SPECIFICATION FOR TEN60 POWER BOARD TO BOARD INTERCONNECT SYSTEMS					29 of 29
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PS-46436-100		PS	001	GJEEVANSURES	SCS02	HTHYA	GARAJ
TEMPLATE FIL	ENAME: 1703070003 REV A						